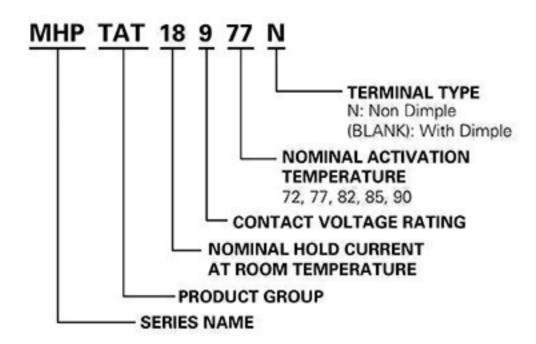
Part Ordering Number System



Application Environment

The device is intended to be used for applications which are common for general electronic devices. Usage in any of the special environments or conditions as listed below may adversely impact the device performance and therefore users should carefully consider conditions of use of the end product and the potential impact on reliability or performance when incorporating this device into any design to carefully examine the actual performance and reliability of the device.

- Environment where the devices are exposed to water, oil, chemical solutions, and/or organic solvents.
- Installation in an area close to a heat source or adjacent to or near flammable objects such as plastic wires.
- Environment in which the device is constrained by pressure, sealing or resin coating.
- Environment where water condenses on the device.
- Environment with salt air or with corrosive gas such as CL₂, H₂S, NH₃, SO₂, and NOX.
- Environment with grit and dust and/or under direct sunlight.
- Environment outside of recommended operating temperature.

Packaging

Packaging Option	Quantity	Quantity & Packaging Code
20,000 pcs. Minimum	1000 pcs/bag	1 bag per inner box 20 inner box in 1 outer box

Precautions for Rating

- a. The power supply voltage must be less than the rated voltage of the device. Operation above the voltage rating may result in device damage, smoke or flame.
- b. Designs must be selected in such a manner that the device hold current is higher than the normal current value in the circuit and that the device trip current is lower than the abnormal current value. Selecting device hold current and trip current values that are too low for the application may interrupt the circuit under normal usage conditions.
- c. This product should not be used in an application where the maximum interrupt current can be exceeded in a short circuit condition.
- d. The devices are intended for protection against damage caused by occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- e. The devices may not perform as specified if mechanical pressure is added while the device is in the tripped state or exposed to temperature conditions over 100°C.